

## Features

- High-Speed Switching
- Low RDS(ON)
- Low Gate Charge
- Capable of 4.5 V Gate Drive
- RoHS and Halogen-Free Compliant
- 100% UIS and RG Tested

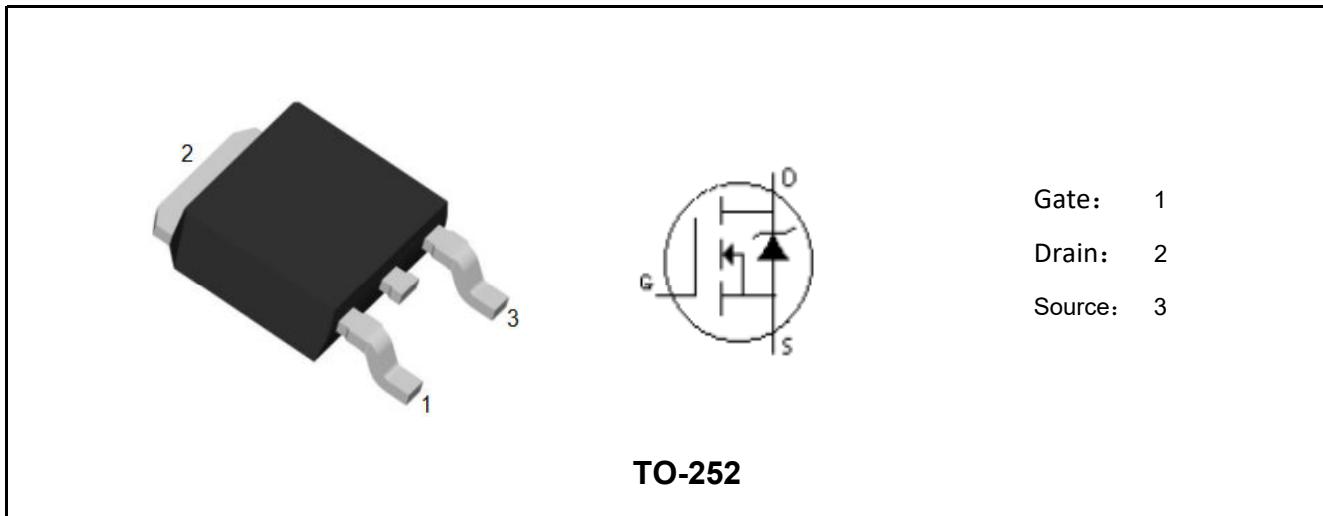
## Product Summary

V <sub>DS</sub>	150	V
I <sub>D</sub>	18	A
R <sub>DS(ON),Typ@10V</sub>	54	mΩ
R <sub>DS(ON),Typ@4.5V</sub>	62	mΩ
Q <sub>g</sub>	8	nC

## Applications

- Synchronous Rectification
- Industrial and Motor Drive
- DC/DC and AC/DC Converters

## Package



## Ordering information

Marking	Package	Packaging	Min. package quantity
LX252F18N15	TO-252	Tape & Reel	3000

Absolute Maximum Ratings( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current $T_c=25^\circ\text{C}$ (Note 1)	$I_D$	18	A
Continuous Drain Current $T_c=100^\circ\text{C}$ (Note 1)		12	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	60	A
Total Dissipation	$P_D$	52	W
Junction Temperature	$T_j$	175	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55-175	$^\circ\text{C}$
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	25	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

## Thermal Characteristics

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	$R_{\theta JC}$	2.9	$^\circ\text{C/W}$
Maximum Junction-to-Ambient (Note 3)	$R_{\theta JA}$	60	$^\circ\text{C/W}$

Note 1: Ensure that the channel temperature does not exceed  $175^\circ\text{C}$ .

Note 2:  $V_{DD}=50\text{V}$ ,  $T_{ch}= 25^\circ\text{C}$ (initial),  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ .

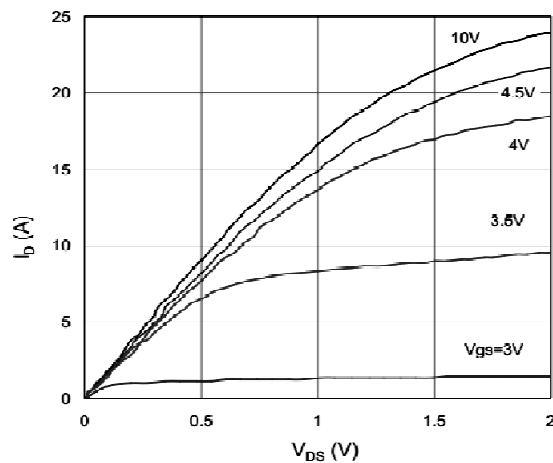
Note 3 : The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

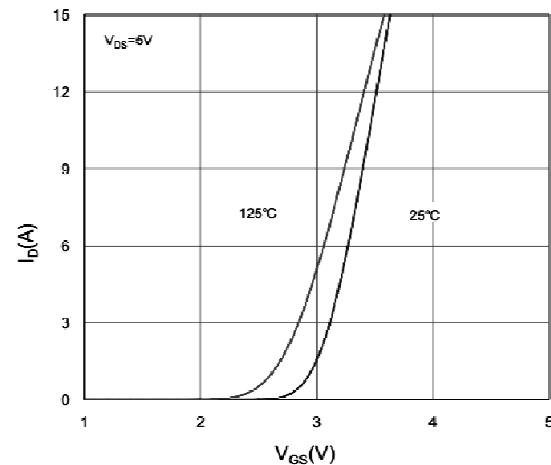
Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	150	-	-	V
Drain-Source Leakage Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=150\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{TH})}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	1.3	2.1	2.6	V
Drain-Source On Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=5\text{A}$	-	62	80	mΩ
		$\text{T}_j=125^\circ\text{C}$	-	122	-	
		$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10\text{A}$	-	54	65	
		$\text{T}_j=125^\circ\text{C}$	-	105	-	
<b>Dynamic Characteristics</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=35\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1.0\text{MHz}$	-	630	-	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	200	-	pF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	7.5	-	pF
Gate Resistance	$\text{R}_g$	$\text{V}_{\text{DS}}=0\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1.0\text{MHz}$	-	3.2	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$\text{VDD}=75\text{V}, \text{ID}=10\text{A}$ $\text{VGS}=10\text{V}, \text{RG}=10\Omega$	-	8	-	ns
Turn-On Rise Time	$t_r$		-	5	-	ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	12	-	ns
Turn-Off Rise Time	$t_f$		-	4	-	ns
Total Gate Charge	$\text{Q}_g$	$\text{VDS}=75\text{V}, \text{ID}=10\text{A}, \text{VGS}=10\text{V}$	-	8	-	nC
	$\text{Q}_g (4.5\text{V})$		-	4	-	
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	2.5	-	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	0.8	-	nC
<b>Source-Drain Characteristics</b>						
Diode Forward Voltage	$\text{V}_{\text{sd}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=10\text{A}$	-	0.8	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$\text{V}_R=75\text{V}, \text{I}_F=10\text{A}, \text{di}/\text{dt}=100\text{A}/\text{us}$	-	45	-	ns
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	55	-	nC

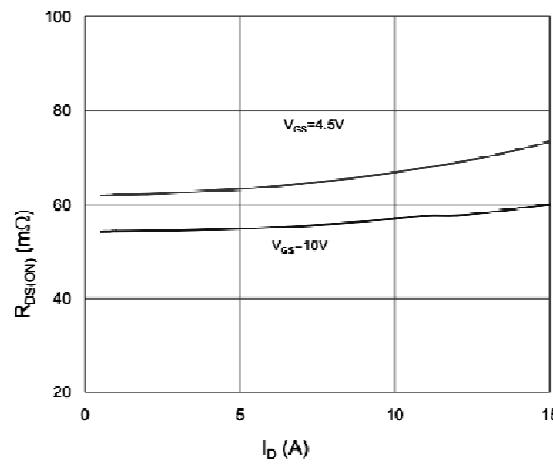
## Characteristics Curves



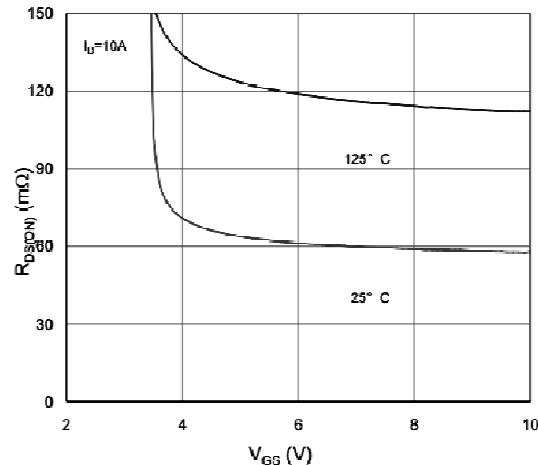
Output Characteristic



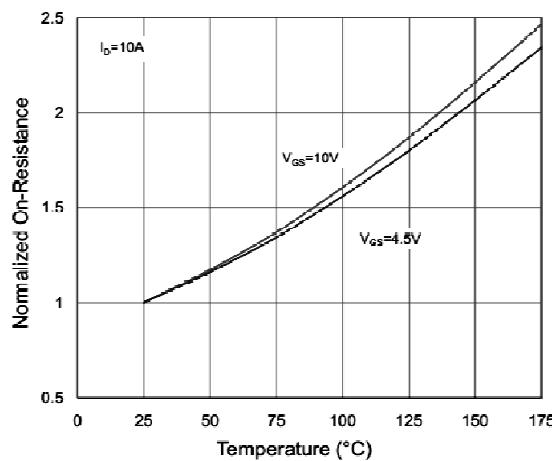
Transfer Characteristic



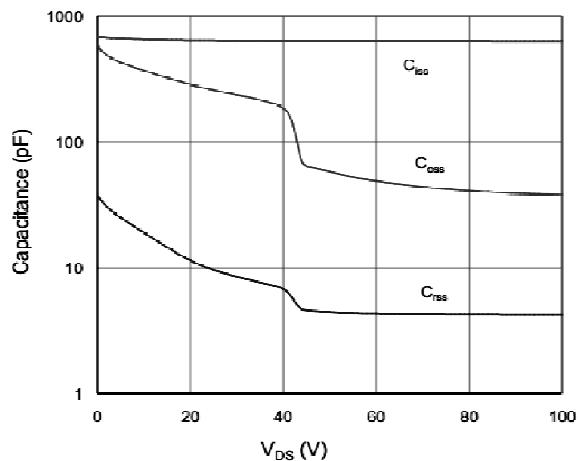
On Resistance Vs Drain Current



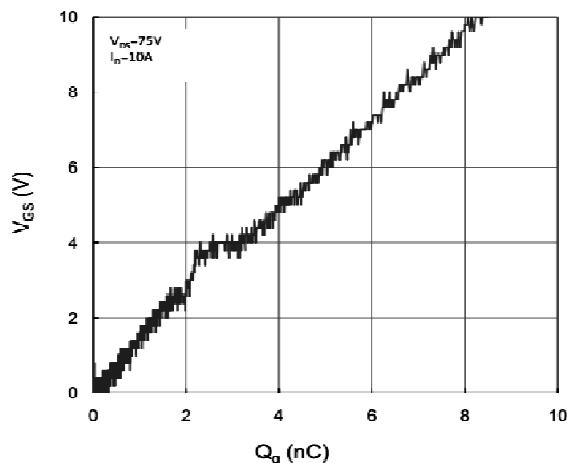
On Resistance Vs Gate Source Voltage



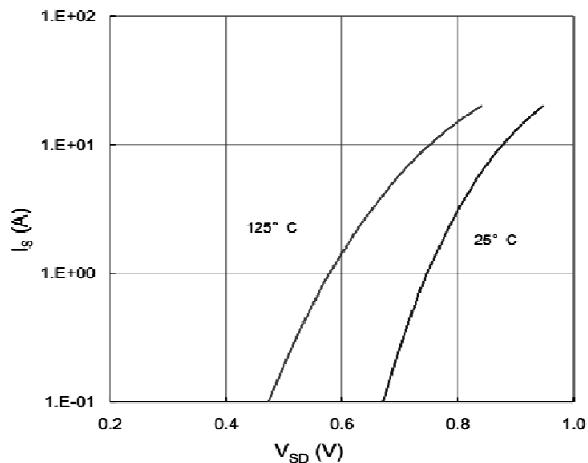
R<sub>dson</sub>-JunctionTemperature



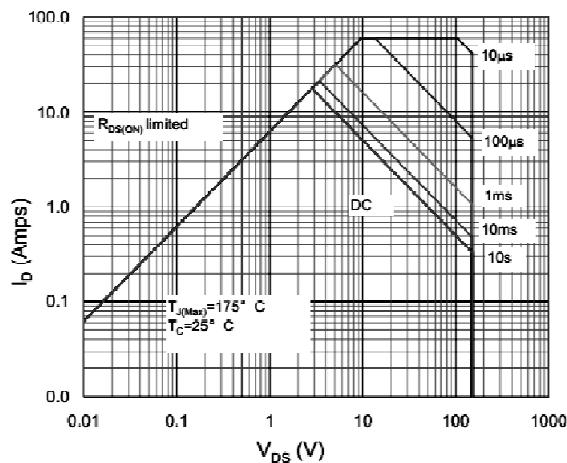
Capacitance



Gate Charge Waveform



Source-Drain Diode Forward Voltage

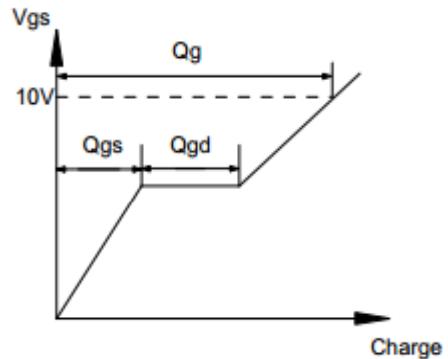
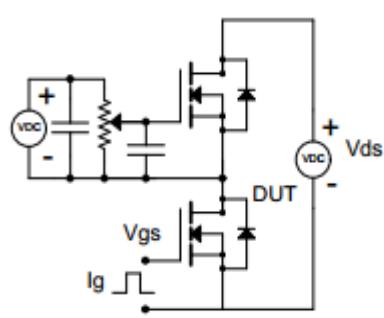


Maximum Safe Operating Area

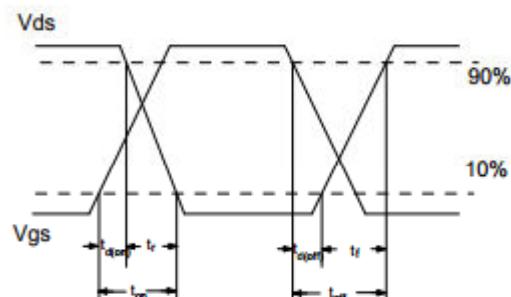
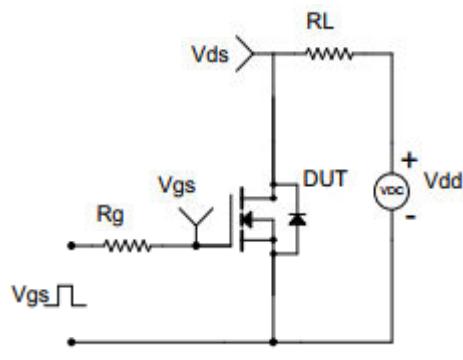
Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

## Test Circuit & Waveform

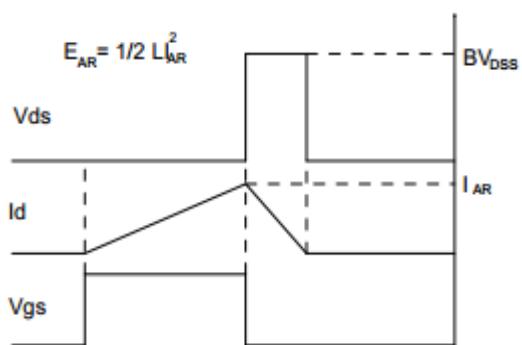
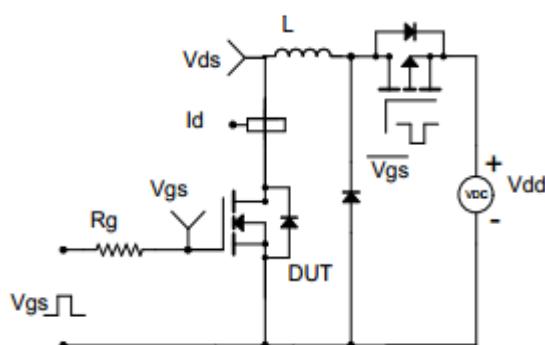
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveform



### Unclamped Inductive Switching (UIS) Test Circuit & Waveform



## TO-252 Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	2.10		2.50	E	5.80		6.30
B	0.80		1.25	e1	2.25	2.30	2.35
b	0.50		0.85	e2	4.45		4.75
b1	0.50		0.90	L1	9.50		10.20
b2	0.45		0.60	L2	0.90		1.45
C	0.45		0.60	L3	0.60		1.10
D	6.35		6.75	K	-0.1		0.10
D1	5.10		5.50				

